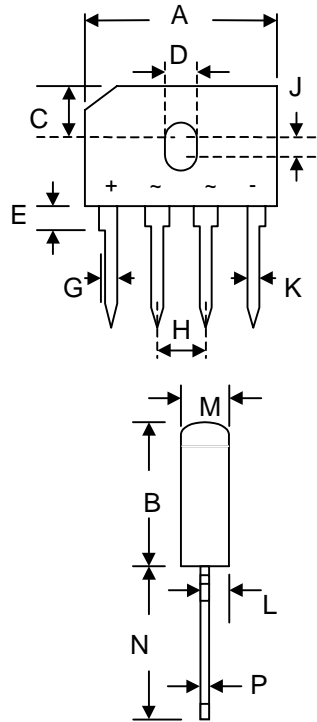


8.0A GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards



GBU		
Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	7.40	7.90
D	3.50	4.10
E	1.52	2.03
G	2.16	2.54
H	4.83	5.33
J	1.65	2.16
K	1.65	2.03
L	0.76	1.02
M	3.30	3.56
N	17.50	18.00
P	0.46	0.56
All Dimensions in mm		

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 4.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBU8A	GBU8B	GBU8D	GBU8G	GBU8J	GBU8K	Unit
Peak Repetitive Reverse Voltage	V _{RRM}							
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	V
DC Blocking Voltage	V _R							
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	V
Average Rectified Output Current	I _O	8.0 6.0						A
		@T _C = 100°C @T _A = 45°C						
Non-Repetitive Peak Forward Surge Current	I _{FSM}	200						A
		8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)						
I ² t Rating for Fusing (t < 8.35ms)	I ² t	166						A ² s
Forward Voltage (per element)	V _{FM}	1.0						V
		@I _F = 8.0A						
Peak Reverse Current	I _R	5.0						μA
		@T _A = 25°C						
		At Rated DC Blocking Voltage						
		@T _C = 100°C						
Typical Thermal Resistance (per leg) (Note 1)	R _{θJA}	18.0						K/W
Typical Thermal Resistance (per leg) (Note 2)	R _{θJC}	3.0						K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150						°C

Note: 1. Thermal resistance junction to ambient, mounted on PCB at 9.5mm lead length with 12mm² copper pads.
2. Thermal resistance junction to case, mounted on 7.5 x 7.5 x 0.3cm thick AL plate.

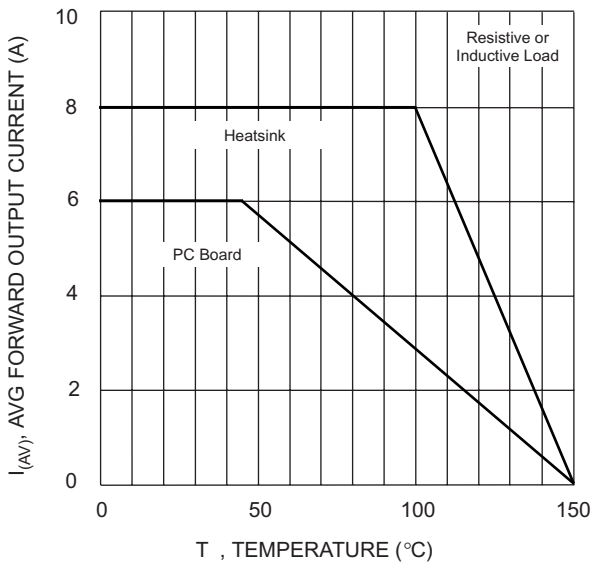


Fig. 1 Forward Current Derating Curve

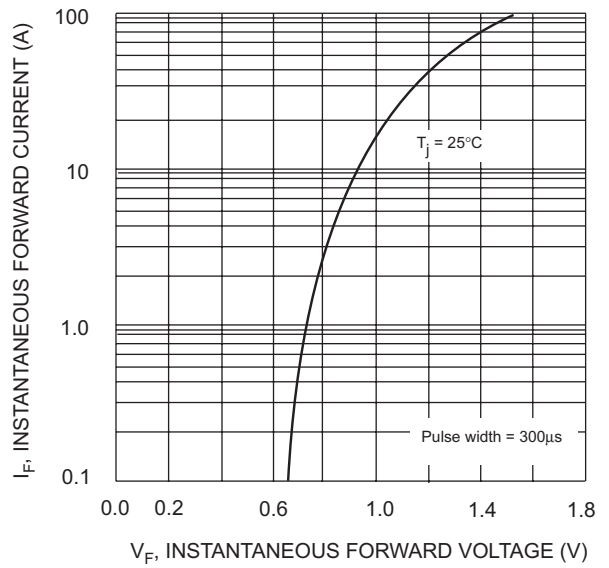


Fig. 2 Typical Forward Characteristics, per element

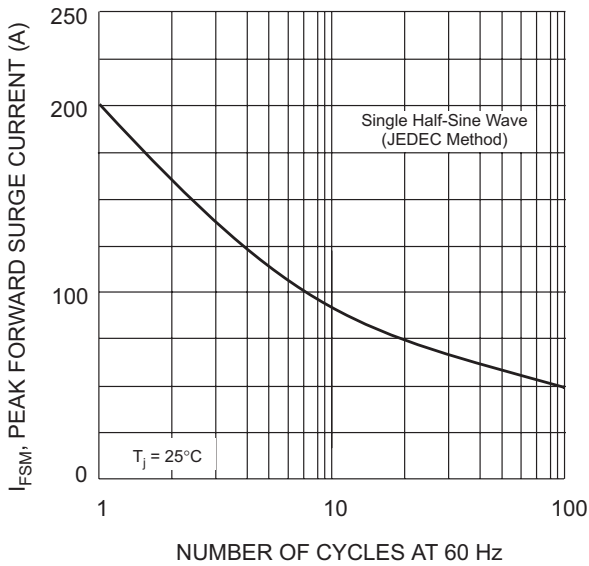


Fig. 3 Maximum Non-Repetitive Surge Current

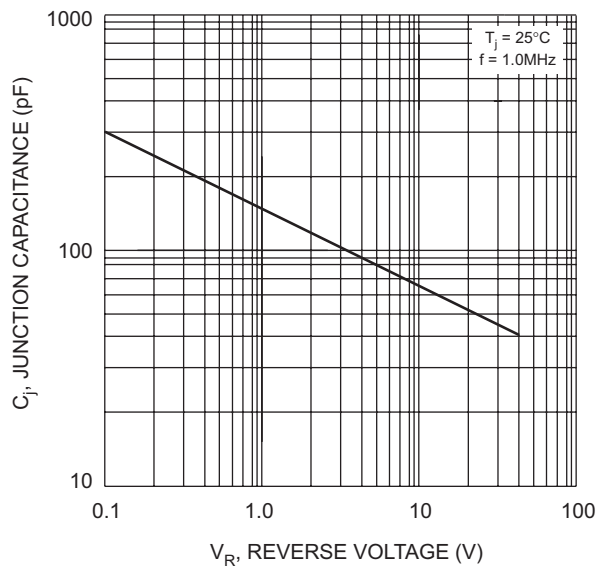


Fig. 4 Typical Junction Capacitance

ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
GBU8A	SIL Bridge	25 Units/Tube
GBU8B	SIL Bridge	25 Units/Tube
GBU8D	SIL Bridge	25 Units/Tube
GBU8G	SIL Bridge	25 Units/Tube
GBU8J	SIL Bridge	25 Units/Tube
GBU8K	SIL Bridge	25 Units/Tube

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

Won-Top Electronics Co., Ltd (WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. Furthermore, this information does not give the purchaser of semiconductor devices any license under patent rights to manufacturer. WTE reserves the right to change any or all information herein without further notice.

WARNING: DO NOT USE IN LIFE SUPPORT EQUIPMENT. WTE power semiconductor products are not authorized for use as critical components in life support devices or systems without the express written approval.

Won-Top Electronics Co., Ltd.

No. 44 Yu Kang North 3rd Road, Chine Chen Dist., Kaohsiung, Taiwan

Phone: 886-7-822-5408 or 886-7-822-5410

Fax: 886-7-822-5417

Email: sales@wontop.com

Internet: <http://www.wontop.com>

We power your everyday.